

DHG50X1200NA

preliminary

 $V_{RRM} = 1200 V$

 $I_{FAV} = 2x \quad 25 A$

 t_{rr} = 200 ns

High Performance Fast Recovery Diode Low Loss and Soft Recovery Parallel legs

Sonic Fast Recovery Diode

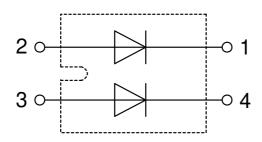
Part number

DHG50X1200NA



Backside: Isolated





Features / Advantages:

- Planar passivated chips
- Very low leakage current
 Vary about reasons times
- Very short recovery time
- Improved thermal behaviour
- Very low Irm-values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low Irm reduces:
 - Power dissipation within the diode
 - Turn-on loss in the commutating switch

Applications:

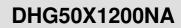
- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

Package: SOT-227B (minibloc)

- Isolation Voltage: 3000 V~
- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Base plate: Copper internally DCB isolated
- Advanced power cycling

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Fast Diode				Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V _{RSM}	max. non-repetitive reverse blockii	ng voltage	$T_{VJ} = 25^{\circ}C$			1200	V
V _{RRM}	max. repetitive reverse blocking vo	oltage	$T_{VJ} = 25^{\circ}C$			1200	V
I _R	reverse current, drain current	V _R = 1200 V	$T_{VJ} = 25^{\circ}C$			30	μΑ
		$V_R = 1200 \text{ V}$	$T_{VJ} = 125^{\circ}C$			0.5	mA
V _F	forward voltage drop	I _F = 25 A	$T_{VJ} = 25^{\circ}C$			2.11	V
		$I_F = 50 \text{ A}$				2.74	٧
		I _F = 25 A	T _{vJ} = 125°C			2.09	٧
		$I_F = 50 A$				2.88	٧
I _{FAV}	average forward current	$T_{C} = 65^{\circ}C$	T _{vJ} = 150°C			25	Α
		rectangular d = 0.5					
V _{F0}	threshold voltage		T _{VJ} = 150°C			1.23	٧
r _F	slope resistance	ss calculation only				30	mΩ
R _{thJC}	thermal resistance junction to case	;				1.2	K/W
R _{thCH}	thermal resistance case to heatsin	k			0.1		K/W
P _{tot}	total power dissipation		$T_C = 25^{\circ}C$			100	W
I _{FSM}	max. forward surge current	$t = 10 \text{ ms}$; (50 Hz), sine; $V_R = 0 \text{ V}$	$T_{VJ} = 45^{\circ}C$			200	Α
C¹	junction capacitance	$V_R = 600 \text{V}$ f = 1 MHz	$T_{VJ} = 25^{\circ}C$		11		pF
I _{RM}	max. reverse recovery current		$T_{VJ} = 25 ^{\circ}\text{C}$		23		Α
		$I_F = 30 \text{ A}; V_R = 600 \text{ V}$	$T_{VJ} = 125$ °C		30		Α
t _{rr}	reverse recovery time	$I_F = 30 \text{ A}; V_R = 600 \text{ V}$ -di _F /dt = 600 A/µs	$T_{VJ} = 25 ^{\circ}C$		200		ns
)	1	$T_{VJ} = 125$ °C		350		ns

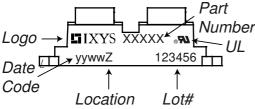


DHG50X1200NA

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Package SOT-227B (minibloc)			Ratings					
Symbol	Definition	Conditions			min.	typ.	max.	Unit
I _{RMS}	RMS current	per terminal					100	Α
T _{VJ}	virtual junction temperatu	re			-40		150	°C
T _{op}	operation temperature				-40		125	°C
T _{stg}	storage temperature				-40		150	°C
Weight						30		g
M _D	mounting torque				1.1		1.5	Nm
$\mathbf{M}_{_{T}}$	terminal torque				1.1		1.5	Nm
d _{Spp/App}	creepage distance on surface striking distance through air			3.2			mm	
$d_{Spb/Apb}$	creepage distance on surface surking distance unough an		terminal to backside	8.6	6.8			mm
V _{ISOL}	isolation voltage	t = 1 second	50/60 Hz. RMS: IISOL ≤ 1 mA		3000			V
		t = 1 minute			2500			V

Product Marking



Part description

D = Diode H = Sonic Fast Recovery Diode

G = extreme fast

50 = Current Rating [A]

X = Parallel legs 1200 = Reverse Voltage [V]

NA = SOT-227B (minibloc)

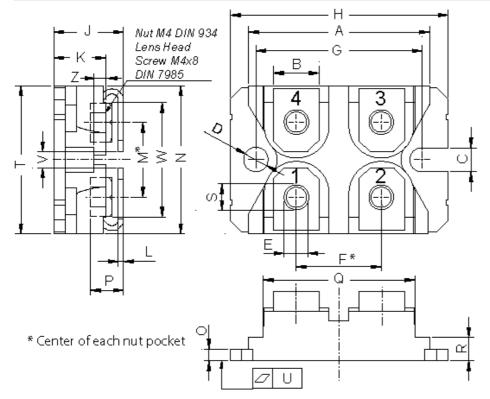
Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DHG50X1200NA	DHG50X1200NA	Tube	10	507766

Equivalent Circuits for Simulation			* on die level	$T_{VJ} = 150^{\circ}C$
$I \rightarrow V_0$)— <u>R</u> o	Fast Diode		
V _{0 max}	threshold voltage	1.23		V
R_{0max}	slope resistance *	28		$m\Omega$

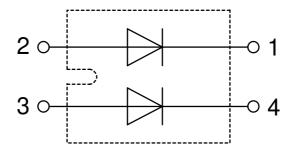


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Outlines SOT-227B (minibloc)



Dim.	Millimeter		Inches		
DIIII.	min	max	min	max	
Α	31.50	31.88	1.240	1.255	
В	7.80	8.20	0.307	0.323	
С	4.09	4.29	0.161	0.169	
D	4.09	4.29	0.161	0.169	
Е	4.09	4.29	0.161	0.169	
F	14.91	15.11	0.587	0.595	
G	30.12	30.30	1.186	1.193	
Н	37.80	38.23	1.488	1.505	
J	11.68	12.22	0.460	0.481	
K	8.92	9.60	0.351	0.378	
L	0.74	0.84	0.029	0.033	
M	12.50	13.10	0.492	0.516	
N	25.15	25.42	0.990	1.001	
0	1.95	2.13	0.077	0.084	
Р	4.95	6.20	0.195	0.244	
Q	26.54	26.90	1.045	1.059	
R	3.94	4.42	0.155	0.167	
S	4.55	4.85	0.179	0.191	
Т	24.59	25.25	0.968	0.994	
U	-0.05	0.10	-0.002	0.004	
V	3.20	5.50	0.126	0.217	
W	19.81	21.08	0.780	0.830	
Ζ	2.50	2.70	0.098	0.106	





Fast Diode

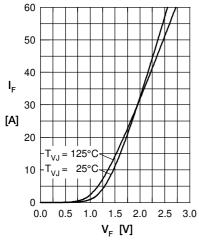


Fig. 1 Typ. Forward current versus V_F

Fig. 4 Dynamic parameters Q_{rr} , I_{RM} versus T_{VJ}

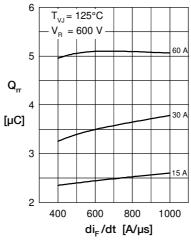


Fig. 2 Typ. reverse recov. charge Q_{rr} versus di/dt

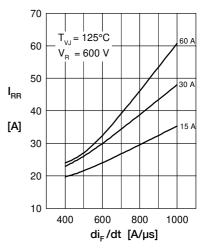


Fig. 3 Typ. peak reverse current I_{RM} versus di/dt

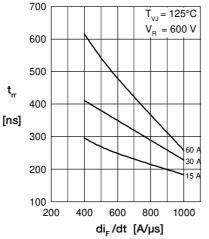


Fig. 5 Typ. recovery time t_{rr} versus di/dt

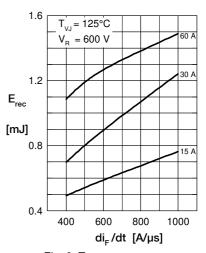


Fig. 6 Typ. recovery energy $E_{\rm rec}$ versus di/dt

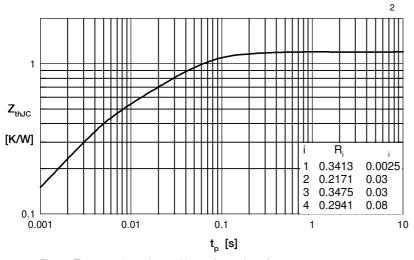


Fig. 7 Typ. transient thermal impedance junction to case